

# **Marking Information**

Site 1



5F = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Kev

Year	2017		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	E		Н	I	J	K	L	M	N	0	Р	R
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2



5F = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020)

W = Week (ex: a = week 27; z represents week 52 and 53)

X = Internal Code (ex: U = Monday)

Date Code Kev

Jale Code Key												
Year	2017		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	7		0	1	2	3	4	5	6	7	8	9
Week	1-26			27-52				53				
Code		Α	-Z			a-z				7	<u>.</u>	
	1	•		1		1						
Internal Code	Sur	1	Mon		Tue	W	ed	Thu		Fri		Sat
Code	Т		11		V	V	V	Y		V		7



## **Maximum Ratings** (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	20	V		
Gate-Source Voltage	$V_{GSS}$	±10	V		
Continuous Drain Current (Note 6) Vgs = 4.5V	lo	6.5 5.2	А		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%		I <sub>DM</sub>	30	A	
Continuous Source-Drain Diode Current	Is	2	Α		
Avalanche Current (Note 7) L = 0.1mH	las	8	Α		
Avalanche Energy (Note 7) L = 0.1mH			Eas	8	mJ

# **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	PD	0.7	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	170	°C/W
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	PD	1.6	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R <sub>0JA</sub>	76	°C/W
Thermal Resistance, Junction to Case (Note 6)	·	Rejc	15	C/VV
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BVDSS	20	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	Igss	_	_	±10	μΑ	$V_{GS} = \pm 10V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	Vgs(TH)	0.5		1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
			14.5	25		$V_{GS} = 4.5V, I_D = 4A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	21	31	mΩ	$V_{GS} = 2.5V, I_D = 4A$	
			41.5	60		VGS = 1.8V, ID = 4A	
Diode Forward Voltage	VsD	_	0.7	1.2	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = 5A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	486	_			
Output Capacitance	Coss	_	92	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	77	_		I = 1.0IVID2	
Gate Resistance	Rg	_	3.2	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	5.9	_			
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	12.3	_	nC	V 40V L 6.5A	
Gate-Source Charge	Qgs	_	0.8	_	nc	$V_{DS} = 10V, I_{D} = 6.5A$	
Gate-Drain Charge	Q <sub>gd</sub>	_	2.2	_			
Turn-On Delay Time	t <sub>D(ON)</sub>	_	3.4	_			
Turn-On Rise Time	t <sub>R</sub>	_	5.4	_		$V_{DS} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	tD(OFF)	_	17.6	_	ns	$R_G = 6\Omega$ , $R_L = 10\Omega$ , $I_D = 1A$	
Turn-Off Fall Time	tF	_	9.3	_			
Reverse Recovery Time	trr	_	7.7	_	ns	IF = 1A, di/dt = 100A/µs	
Reverse Recovery Charge	Q <sub>RR</sub>	—-	1.5	_	nC	I <sub>F</sub> = 1A, di/dt = 100A/μs	

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

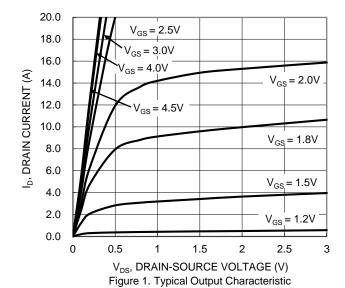
<sup>6.</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

7. IAS and EAS ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.

<sup>8.</sup> Short duration pulse test used to minimize self-heating effect.

<sup>9.</sup> Guaranteed by design. Not subject to product testing.





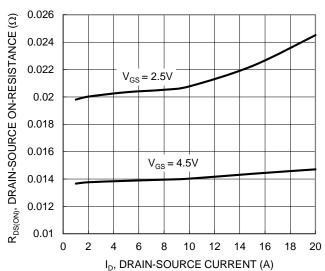


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

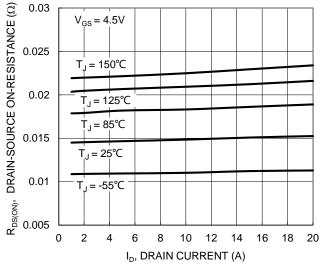


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

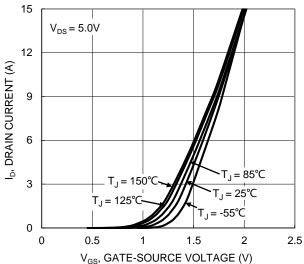


Figure 2. Typical Transfer Characteristic

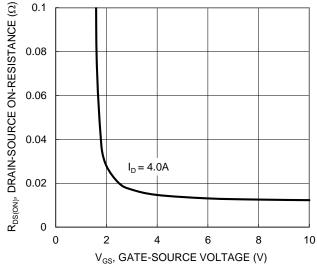


Figure 4. Typical Transfer Characteristic

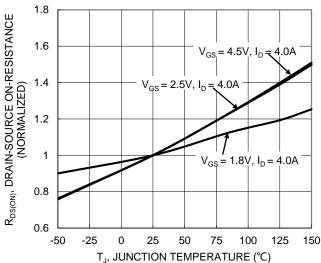


Figure 6. On-Resistance Variation with Junction Temperature



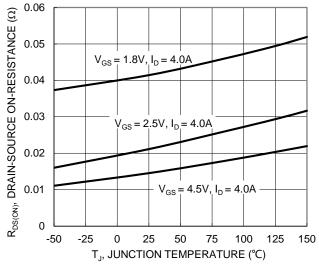


Figure 7. On-Resistance Variation with Junction Temperature

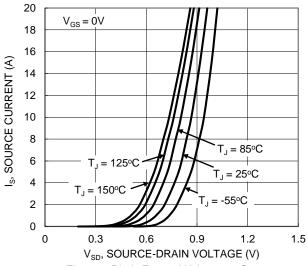


Figure 9. Diode Forward Voltage vs. Current

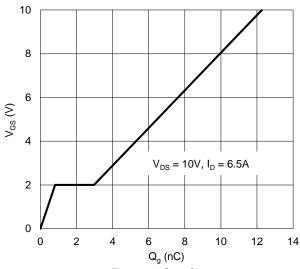


Figure 11. Gate Charge

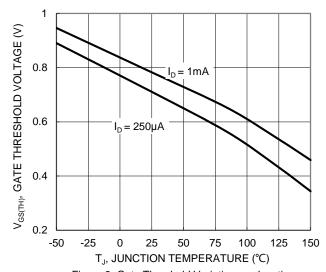


Figure 8. Gate Threshold Variation vs. Junction Temperature

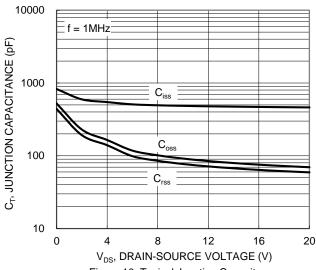
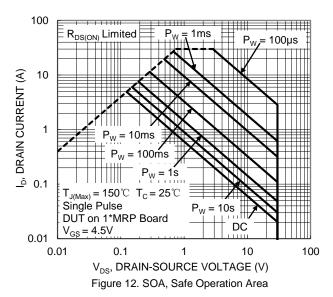


Figure 10. Typical Junction Capacitance





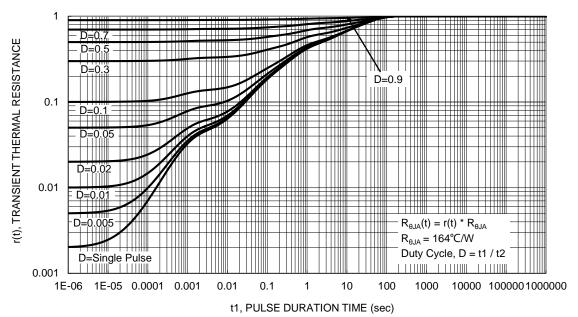


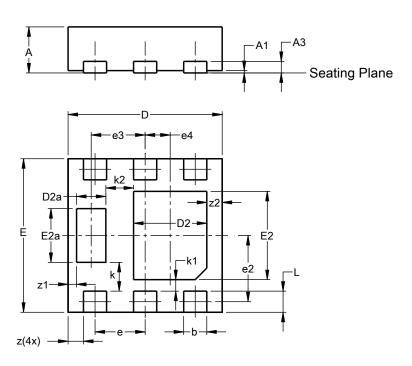
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (Type F)

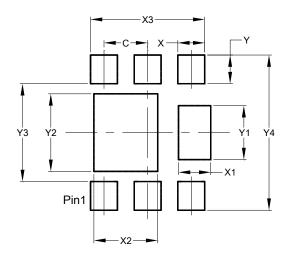


U-DFN2020-6								
	(Type F)							
Dim	Min Max Typ							
Α	0.57	0.63	0.60					
A1	0.00	0.05	0.03					
A3	-	-	0.15					
b	0.25	0.35	0.30					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
D2a	0.33	0.43	0.38					
Е	1.95	2.05	2.00					
E2	1.05	1.25	1.15					
E2a	0.65	0.75	0.70					
е	0.65 BSC							
e2	(	).863 BS	SC					
е3		0.70 BS	С					
e4	0.325 BSC							
k	0.37 BSC							
k1	0.15 BSC							
k2	0.36 BSC							
L	0.225	0.325	0.275					
Z	0.20 BSC							
<b>z</b> 1	0.110 BSC							
z2		0.20 BS	_					
All C	imens	ions in	mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (Type F)



Dimensions	Value (in mm)			
С	0.650			
Х	0.400			
X1	0.480			
X2	0.950			
Х3	1.700			
Υ	0.425			
Y1	0.800			
Y2	1.150			
Y3	1.450			
Y4	2.300			



#### **IMPORTANT NOTICE**

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

#### LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2020, Diodes Incorporated

www.diodes.com